

SOT785-1

plastic low profile fine-pitch ball grid array package; 180 balls; body 14 x 14 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA180
Package type industry code	LFPGA180
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	30-9-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.4	1.4	mm
A ₂	package height	0.8	-	0.9	1	mm
n ₂	actual quantity of termination	-	-	180	-	



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2. Package outline

LFBGA180: plastic low profile fine-pitch ball grid array package; 180 balls; body 14 x 14 x 0.9 mm SOT785-1

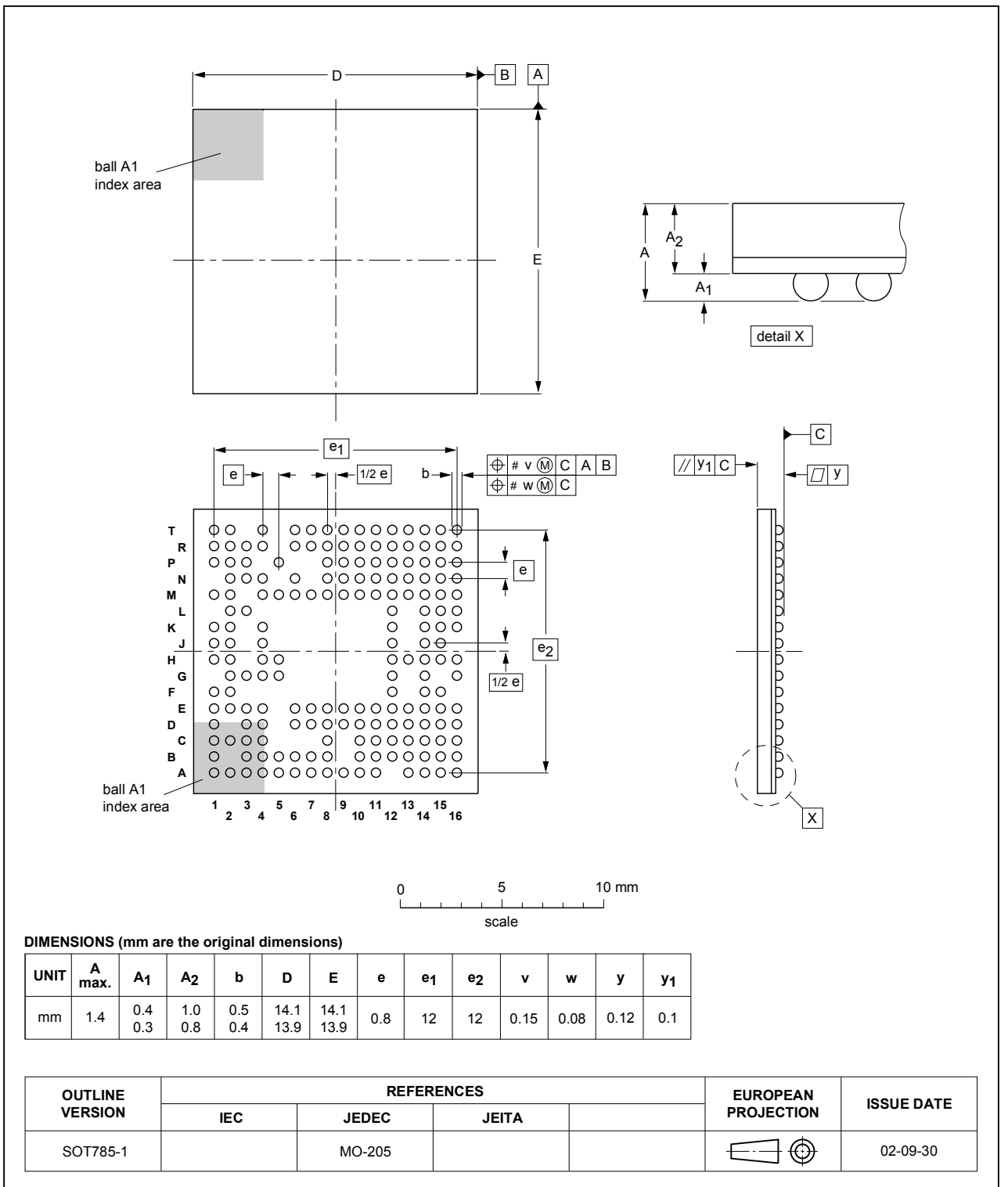


Fig. 1. Package outline LFBGA180 (SOT785-1)

3. Soldering

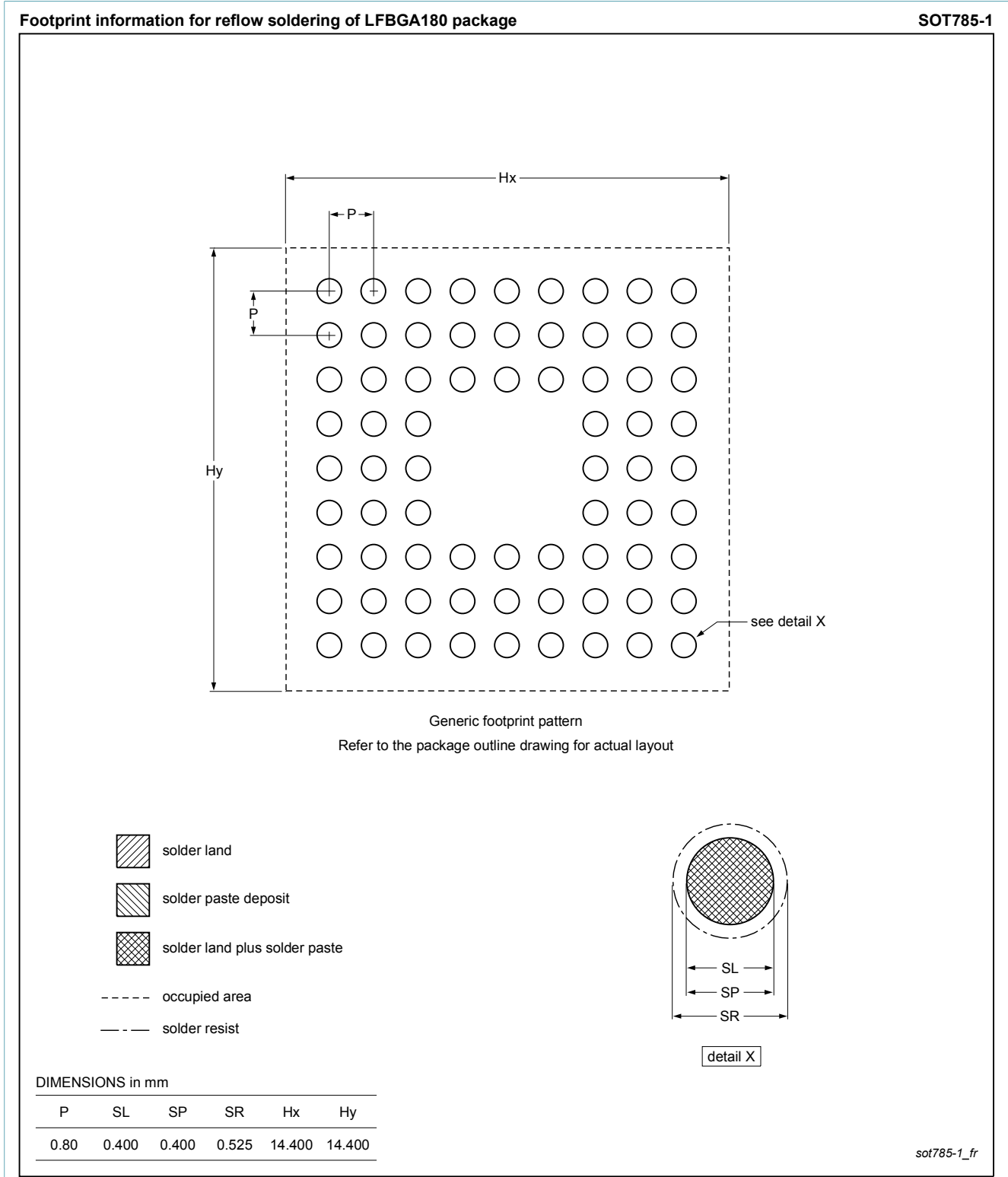


Fig. 2. Reflow soldering footprint for LFBGA180 (SOT785-1)

4. Legal information

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